

# **Data sheet**

SAW duplexer WCDMA / LTE band 4

Series/type: B8673

Ordering code: B39212B8673P810

Date: July 22, 2019

Version: 2.3

DCN: 80-PA243-362 Rev. B

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RF360 Europe GmbH
A Qualcomm – TDK Joint Venture

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Please read **Cautions and warnings** and **Important notes** at the end of this document.

Page 2 of 25



# RF360 Europe GmbH A Qualcomm – TDK Joint Venture

# **Table of contents**

1 Application	
2 Features.	
3 Package	
4 Pin configuration	
5 Matching circuit	
6 Characteristics.	
7 Maximum ratings	11
8 Transmission coefficients	
9 Reflection coefficients	
10 <u>EVMs</u>	16
11 Packing material	
12 Marking	21
13 Soldering profile	22
14 Annotations.	
15 Cautions and warnings	24
16 Important notes	25



# RF360 Europe GmbH A Qualcomm – TDK Joint Venture

# 1 Application

- Low-loss SAW duplexer for mobile telephone WCDMA/ LTE Band 4 systems
- Low insertion attenuation
- Low amplitude ripple
- Usable pass band 45 MHz
- High isolation between Tx and Rx

#### 2 Features

- Package size 1.8±0.1 mm × 1.4±0.1 mm
- Package height 0.475 mm (max.)
- Approximate weight 4 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

Pin configuration

■ 2, 4, 5, 7, 8 Ground

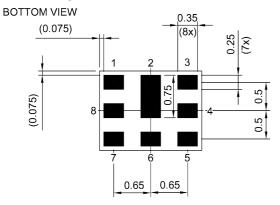
RX

TX

**ANT** 

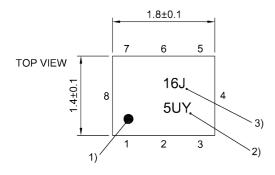
#### 3 **Package**

SIDE VIEW

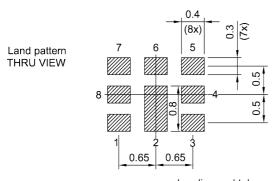


Pad and pitch tolerance ±0.05

# 



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number



Landing pad tolerance -0.02

Figure 1: Drawing of package with package height A = 0.475 mm (max.). See Sec. Package information (p. 24).

Page 5 of 25

# 5 Matching circuit

■  $L_{p6}$  = 3.3 nH

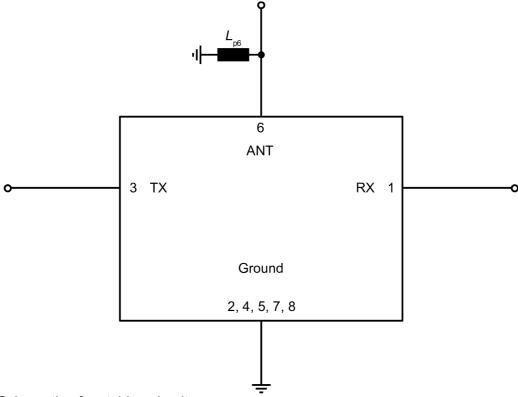


Figure 2: Schematic of matching circuit.

External shunt inductor for ESD protection is recommended at any ports towards antenna.

#### 6 Characteristics

# 6.1 TX - ANT

Temperature range for specification  $T_{\text{SPEC}} = -30 \,^{\circ}\text{C} \dots +85 \,^{\circ}\text{C}$ 

TX terminating impedance  $Z_{Tx} = 50 \Omega$ 

ANT terminating impedance  $Z_{\Delta NT} = 50 \Omega // 3.3 \text{ nH}^{1)}$ 

RX terminating impedance  $Z_{\rm RX}$  = 50  $\Omega$ 

Characteristics TX – ANT					$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	<b>typ.</b> @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{\tiny SPEC}} \end{array}$	
Center frequency				f <sub>C</sub>	_	1732.5	_	MHz
Maximum insertion attenuation								
		1710 1755	MHz	$\alpha_{\text{max}}$	_	1.5	2.0	dB
	@f <sub>carrier</sub>	1712.4 1752.6	MHz	$\alpha_{\text{WCDMA},\text{max}}^{\qquad 2)}$	_	1.5	2.0	dB
Amplitude ripple (p-p)								
		1710 1755	MHz	$\Delta \alpha_{3)}$	_	0.5	1.0	dB
	@f <sub>carrier</sub>	1712.4 1752.6	MHz	$\Delta\alpha_{\text{WCDMA}}^{2),3)}$	_	0.4	1.0	dB
Maximum VSWR				$VSWR_{max}$				
@ TX port		1710 1755	MHz		_	1.7	2.0	
@ ANT port		1710 1755	MHz		_	1.5	2.0	
Maximum error vector magnitude				$EVM_{max}^{}4)}$				
		1712.4 1752.6	MHz		_	1.0	2.0	%
Minimum attenuation								
		10 729	MHz	$\boldsymbol{\alpha}_{\text{min}}$	30	41	_	dB
		728 764	MHz	$\boldsymbol{\alpha}_{\text{min}}$	37	41	_	dB
		851 894	MHz	$\boldsymbol{\alpha}_{_{min}}$	35	39	_	dB
		1565 1573	MHz	$\boldsymbol{\alpha}_{_{min}}$	40	45	_	dB
		1573 1577	MHz	$\boldsymbol{\alpha}_{\text{min}}$		45	_	dB
		1577 1585	MHz	$\alpha_{min}$		43	_	dB
		1598 1606	MHz	$\boldsymbol{\alpha}_{\text{min}}$		37	_	dB
		1805 1880	MHz	$\alpha_{_{min}}$	20	42	_	dB
		1930 1990	MHz	$\alpha_{min}$	40	43	_	dB
	@f <sub>carrier</sub>	2112.4 2152.6	MHz	α <sub>WCDMA,min</sub> 2)	37	40	_	dB
	ounce	2400 2500	MHz	α <sub>min</sub>	30	35	_	dB
		3420 3510	MHz	α <sub>min</sub>	24	27	_	dB
		4900 5950	MHz	α <sub>min</sub>		11	_	dB

<sup>&</sup>lt;sup>1)</sup> See Sec. Matching circuit (p. 6).

Attenuation of WCDMA signal ("power transfer function"). Please refer to definition of Power Transfer Function (PTF) of WCDMA signal (p. 23).

<sup>3)</sup> Over any 20MHz.

<sup>&</sup>lt;sup>4)</sup> Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.



#### 6.2 ANT - RX

Temperature range for specification  $T_{\text{SPEC}} = -30 \,^{\circ}\text{C} \dots +85 \,^{\circ}\text{C}$ 

TX terminating impedance  $Z_{TX} = 50 \Omega$ 

ANT terminating impedance  $Z_{ANT} = 50 \Omega // 3.3 \text{ nH}^{1)}$ 

RX terminating impedance  $Z_{RX} = 50 \Omega$ 

Characteristics ANT – RX					$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	<b>typ.</b> @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Center frequency				f <sub>C</sub>	_	2132.5	_	MHz
Maximum insertion attenuation								
		2110 2155	MHz	$\boldsymbol{\alpha}_{\text{max}}$	_	2.1	2.5	dB
	@f <sub>carrier</sub>	2112.4 2152.6	MHz	$\alpha_{\text{WCDMA,max}}^{\qquad 2)}$	_	2.0	2.4	dB
Amplitude ripple (p-p)								
		2110 2155	MHz	$\Delta\alpha_{^{3)}}$	_	0.6	1.0	dB
	@f <sub>carrier</sub>	2112.4 2152.6	MHz	$\Delta\alpha_{\text{WCDMA}}^{2),3)}$	_	0.5	1.0	dB
Maximum VSWR				$VSWR_{max}$				
@ ANT port		2110 2155	MHz		_	1.4	2.0	
@ RX port		2110 2155	MHz		_	1.6	2.0	
Maximum error vector magnitude				$EVM_{max}^{}a)}$				
		2112.4 2152.6	MHz		_	2.0	3.0	%
Minimum attenuation								
		10 1710	MHz	$\boldsymbol{\alpha}_{\text{min}}$	40	51	_	dB
	@f <sub>carrier</sub>	1712.4 1752.6	MHz	$\alpha_{\text{WCDMA,min}}^{\qquad 2)}$	45	60	_	dB
		1755 1910	MHz	$\alpha_{_{min}}$	45	53	_	dB
		1910 1955	MHz	$\boldsymbol{\alpha}_{\text{min}}$	30	51	_	dB
		1955 2025	MHz	$\boldsymbol{\alpha}_{\text{min}}$		42	_	dB
		2255 6000	MHz	$\alpha_{min}$	32	39	_	dB

<sup>&</sup>lt;sup>1)</sup> See Sec. Matching circuit (p. 6).

Attenuation of WCDMA signal ("power transfer function"). Please refer to definition of Power Transfer Function (PTF) of WCDMA signal (p. 23).

<sup>3)</sup> Over any 20MHz.

<sup>&</sup>lt;sup>4)</sup> Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.



#### 6.3 TX - RX

Temperature range for specification  $T_{\text{SPEC}} = -30 \,^{\circ}\text{C} \dots +85 \,^{\circ}\text{C}$ 

TX terminating impedance  $Z_{TY} = 50 \Omega$ 

ANT terminating impedance  $Z_{\Delta NT} = 50 \Omega // 3.3 \text{ nH}^{1)}$ 

RX terminating impedance  $Z_{RX} = 50 \Omega$ 

Characteristics TX – RX					min.	typ.	max.	
					101 / SPEC	@ +25 °C	for $T_{\text{SPEC}}$	
Minimum isolation								
		1574 1577	MHz	$\boldsymbol{\alpha}_{\text{min}}$	40	63	_	dB
		1710 1755	MHz	$\boldsymbol{\alpha}_{\text{min}}$	55	58	_	dB
	@f <sub>carrier</sub>	1712.4 1752.6	MHz	$\alpha_{\text{WCDMA,min}}^{\qquad 2)}$	55	59	_	dB
		2110 2155	MHz	$\boldsymbol{\alpha}_{\text{min}}$	47	50	_	dB
	@f <sub>carrier</sub>	2112.4 2152.6	MHz	$\alpha_{\text{WCDMA,min}}^{\qquad 2)}$	48	51	_	dB
		3410 3520	MHz	$\boldsymbol{\alpha}_{\text{min}}$	20	53	_	dB
		5120 5275	MHz	$\boldsymbol{\alpha}_{\text{min}}$	20	46	_	dB

<sup>&</sup>lt;sup>1)</sup> See Sec. Matching circuit (p. 6).

Attenuation of WCDMA signal ("power transfer function"). Please refer to definition of Power Transfer Function (PTF) of WCDMA signal (p. 23).



# 6.4 Linearity

Temperature range for specification  $T_{\text{SPEC}} = -30 \,^{\circ}\text{C} \dots +85 \,^{\circ}\text{C}$ 

TX terminating impedance  $Z_{TY} = 50 \Omega$ 

ANT terminating impedance  $Z_{\Delta NT} = 50 \Omega // 3.3 \text{ nH}^{1)}$ 

RX terminating impedance  $Z_{RX} = 50 \Omega$ 

Characteristics			$\begin{array}{c} \textbf{min.} \\ \textbf{for } T_{\mathtt{SPEC}} \end{array}$	<b>typ.</b> @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
IMD product levels						
IMD2 <sup>2)</sup>						
Blocker 1	400	MHz	_	-122	-106	dBm
Blocker 3	3865	MHz	_	-112	-102	dBm
IMD3 <sup>2)</sup>						
Blocker 2	1332.5	MHz	_	-125	-109	dBm
Blocker 4	5597.5	MHz	_	-136	-109	dBm

<sup>&</sup>lt;sup>1)</sup> See Sec. Matching circuit (p. 6).

IMD product level limits for power levels  $P_{\text{TX}}$  = 21.5 dBm (antenna port output power) and  $P_{\text{blocker}}$  = -15 dBm (antenna port input power).



# 7 Maximum ratings

Storage temperature	T <sub>STG</sub> <sup>1)</sup> = -40 °C +85 °C	
DC voltage	$ V_{DC}  = 5.0 \text{ V (max.)}^{2}$	
ESD voltage		
	$V_{\rm ESD}^{3)} = 50  \text{V (max.)}$	Machine model.
	$V_{ESD}^{4)} = >100 \text{ V (max.)}$	Human body model.
	$V_{ESD}^{5} = >100 \text{ V (max.)}$	Charged device model.
Input power	P <sub>IN</sub>	
@ TX port: 1710 1755 MHz	29 dBm	Continuous wave for 5000 h @ 50 °C.
@ TX port: other frequency ranges	10 dBm	Continuous wave for 5000 h @ 50 °C.

Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.

<sup>&</sup>lt;sup>2)</sup> 168h Damp Heat Steady State acc. IEC 60068-2-67 Cy.

According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

<sup>&</sup>lt;sup>4)</sup> According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

<sup>&</sup>lt;sup>5)</sup> According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.

# 8 Transmission coefficients

# 8.1 TX - ANT 0.0 1.0 1.072 2.0 3.0 4.0 1720 1740 1760 1780 1700 1800 $f/{\sf MHz}$ 0.0 20.0 40.0 60.0 80.0 <u>-- .</u> 1500 1700 2200 1600 1800 1900 2000 2100 2300 f/MHz 0.0 20.0 40.0 60.0 80.0 1000 2000 3000 4000 5000 6000

Figure 3: Attenuation TX – ANT.

f/MHz

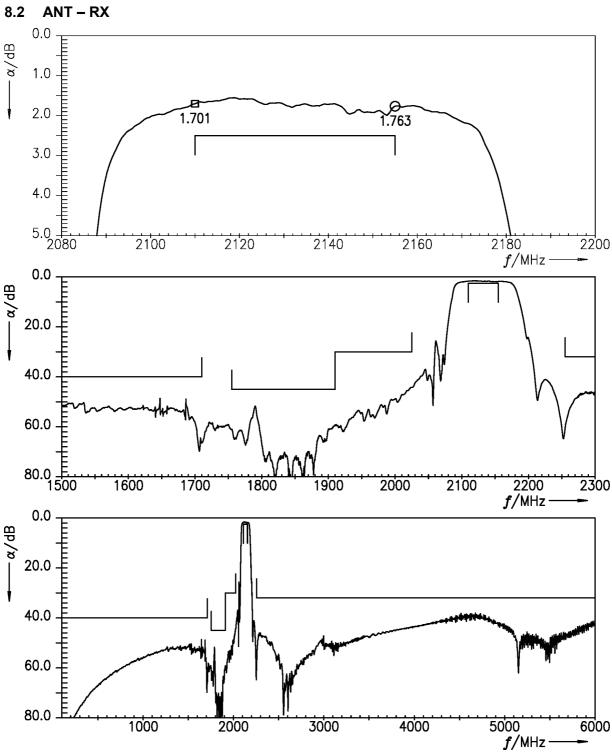


Figure 4: Attenuation ANT – RX.

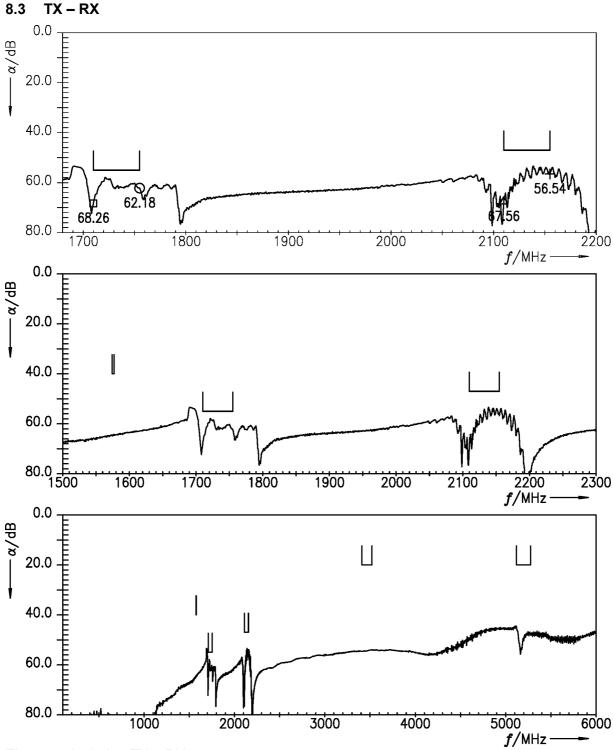
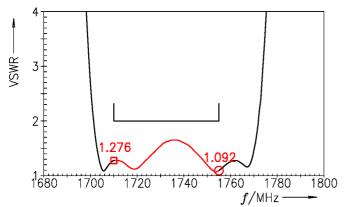
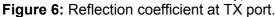
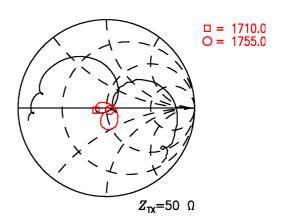


Figure 5: Isolation TX – RX.

# 9 Reflection coefficients







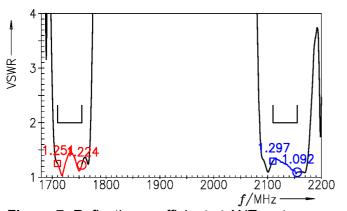
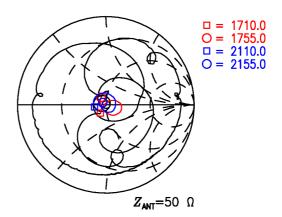


Figure 7: Reflection coefficient at ANT port.



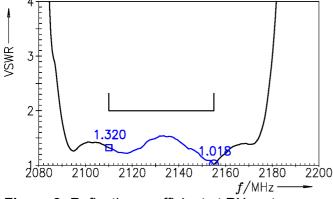
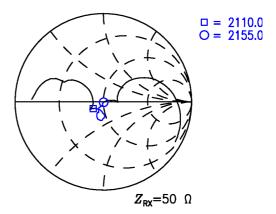


Figure 8: Reflection coefficient at RX port.



# 10 EVMs

# 10.1 TX - ANT

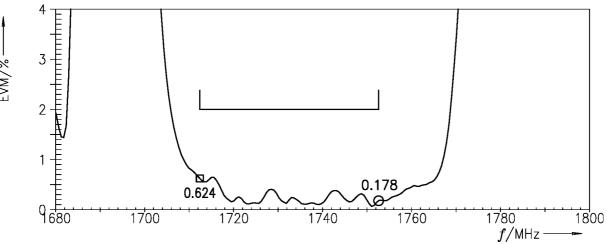


Figure 9: Error vector magnitude TX – ANT.

# 10.2 ANT - RX

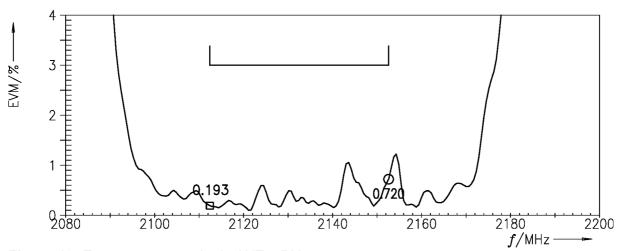
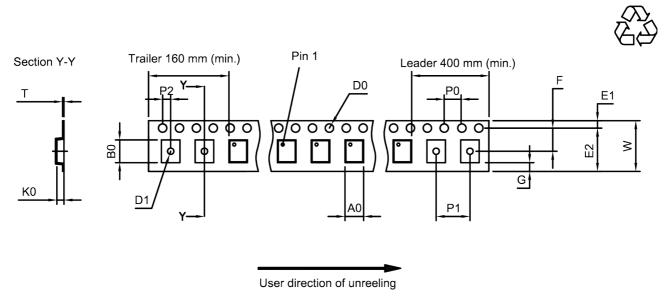


Figure 10: Error vector magnitude ANT – RX.

# 11 Packing material

# 11.1 Tape



**Figure 11:** Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A <sub>0</sub>	1.62±0.05 mm	_	E <sub>2</sub>	6.25 mm (min.)	_	P <sub>1</sub>	4.0±0.1 mm
B <sub>0</sub>	2.04±0.05 mm		F	3.5±0.05 mm		$P_2$	2.0±0.05 mm
D <sub>0</sub>	1.5±0.05 mm	_	G	0.75 mm (min.)	_	Т	0.25±0.02 mm
D <sub>1</sub>	0.8±0.05 mm		K <sub>0</sub>	0.62±0.05 mm		W	8.0±0.1 mm
E <sub>1</sub>	1.75 <sub>±0.1</sub> mm	<del>-</del>	P <sub>0</sub>	4.0±0.1 mm	_		

Table 1: Tape dimensions.

#### 11.2 Reel with diameter of 180 mm

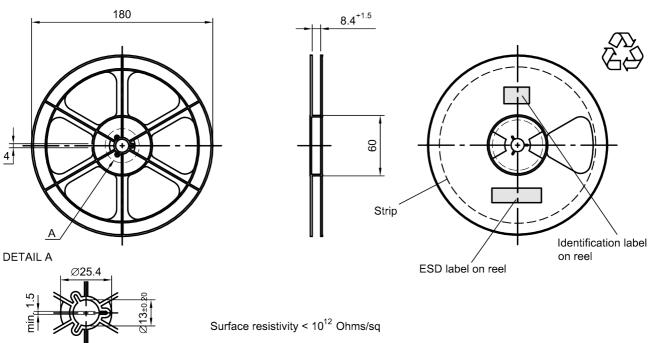


Figure 12: Drawing of reel (first-angle projection) with diameter of 180 mm.

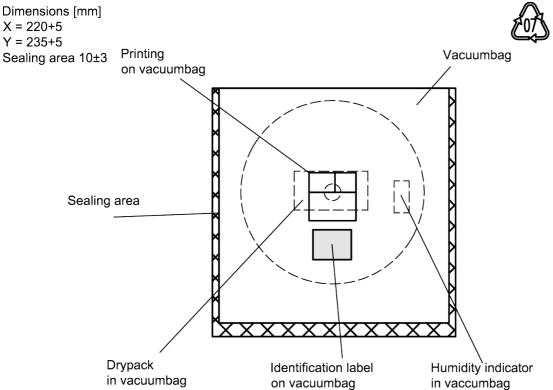


Figure 13: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

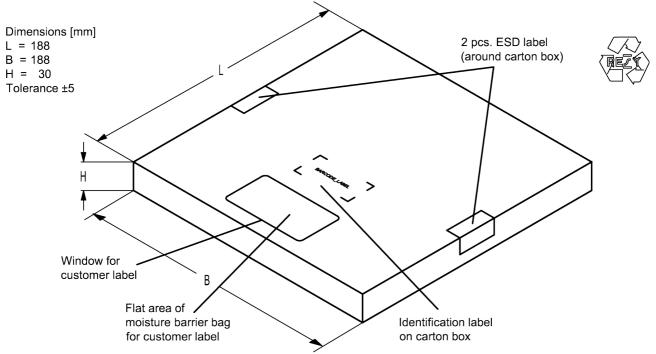
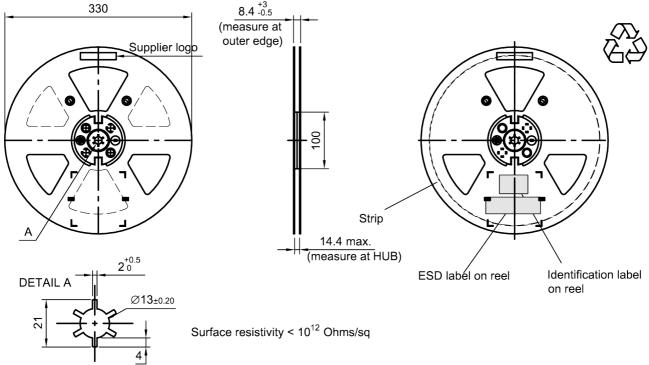


Figure 14: Drawing of folding box for reel with diameter of 180 mm.

# 11.3 Reel with diameter of 330 mm



**Figure 15:** Drawing of reel (first-angle projection) with diameter of 330 mm.

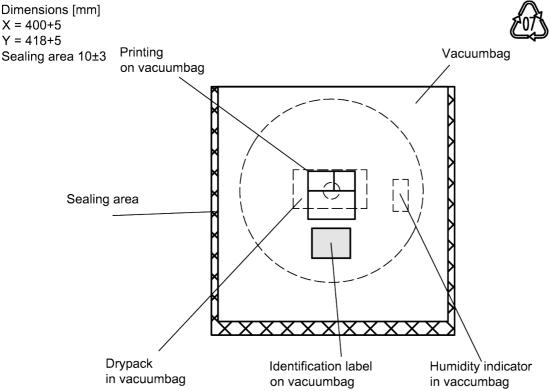


Figure 16: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

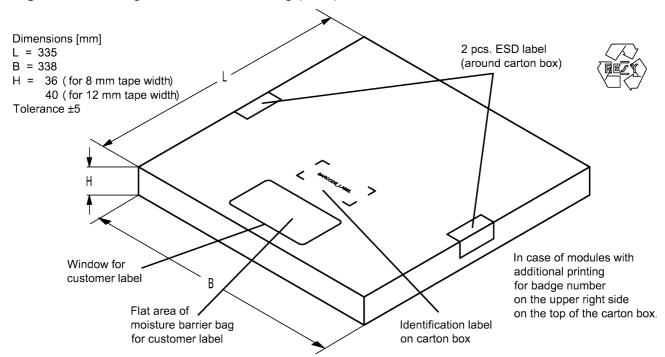


Figure 17: Drawing of folding box for reel with diameter of 330 mm.



# 12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

# ■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J => 1234 1 x  $32^2$  + 6 x  $32^1$  + 18 (=J) x  $32^0$  = 1234

The BASE32 code for product type B8673 is 8F1.

#### ■ Lot number:

The last 5 digits of the lot number, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY => 12345 5 x 47<sup>2</sup> + 27 (=U) x 47<sup>1</sup> + 31 (=Y) x 47<sup>0</sup> = 12345

Adopted BASE32 code for type number						
Decimal	Base32	Decimal	Base32			
value	code	value	code			
0	0	16	G			
1	1	17	Н			
2	2	18	J			
3	3	19	K			
4	4	20	М			
5	5	21	N			
6	6	22	Р			
7	7	23	Q			
8	8	24	R			
9	9	25	S			
10	Α	26	Т			
11	В	27	V			
12	С	28	W			
13	D	29	Х			
14	E	30	Y			
15	F	31	Z			

Adopted BASE47 code for lot number							
Decimal	Base47	Decimal	Base47				
value	code	value	code				
0	0	24	R				
1	1	25	S				
2	2	26	T				
3	3	27	U				
4	4	28	V				
5	5	29	W				
6	6	30	X				
7	7	31	Y				
8	8	32	Z				
9	9	33	b				
10	Α	34	d				
11	В	35	f				
12	С	36	h				
13	D	37	n				
14	E	38	r				
15	F	39	t				
16	G	40	V				
17	Н	41	\				
18	J	42	?				
19	K	43	{				
20	L	44	}				
21	М	45	<				
22	N	46	>				
23	Р						

**Table 2:** Lists for encoding and decoding of marking.

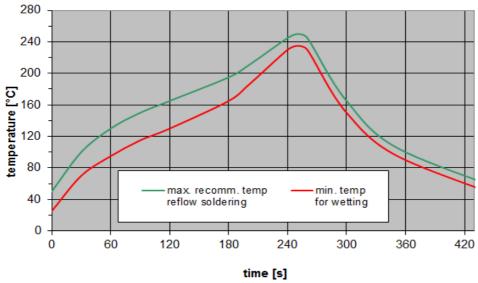


# 13 Soldering profile

The recommended soldering process is in accordance with IEC  $60068-2-58-3^{rd}$  edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature T <sub>peak</sub>	250 °C +0/-5 °C
wetting temperature $T_{min}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

**Table 3:** Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 18:** Recommended reflow profile for convection and infrared soldering – lead-free solder.

#### 14 Annotations

# 14.1 Power Transfer Function (PTF) of WCDMA signal

Attenuation of WCDMA signal,  $\alpha_{_{WCDMA}},$  is defined by

$$\alpha_{\text{WCDMA}}(f_{\text{carrier}}) = 10 \log_{10} \left| \frac{1}{\text{PTF}(f_{\text{carrier}})} \right| dB$$

and

$$PTF(f_{carrier}) = \int_{-\infty}^{+\infty} |S_{21}(f)H_{RRC}(f - f_{carrier})|^2 df$$

with  $f_{\text{carrier}}$  according to 3GPP TS 25.101 (e.g., for the WCDMA B8 pass band,  $f_{\text{carrier}}$  ranges from 882.4 MHz to 912.6 MHz which correspond to the lowest and highest TX channels, respectively).  $H_{\text{RRC}}(f)$  is the transfer function of the root-raised cosine transmit pulse shaping filter according to 3GPP TS 25.101 using the normalization

$$\int_{-\infty}^{+\infty} \left| H_{RRC}(f) \right|^2 \mathrm{d}f = 1 \quad .$$

# 14.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

#### 14.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

#### 14.4 Ordering codes and packing units

Ordering code	Packing unit
B39212B8673P810	15000 pcs
B39212B8673P810S 5	5000 pcs

Table 4: Ordering codes and packing units.

# 15 Cautions and warnings

# 15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <a href="https://www.rf360jv.com/orderingcodes">www.rf360jv.com/orderingcodes</a>.

#### 15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

# 15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

# 15.4 Package information

# Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

#### **Dimensions**

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

#### **Projection method**

Unless otherwise specified first-angle projection is applied.



# 16 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
- 3. The warnings, cautions and product-specific notes must be observed.
- 4. In order to satisfy certain technical requirements, some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous). Useful information on this will be found in our Material Data Sheets on the Internet (<a href="www.rf360jv.com/material">www.rf360jv.com/material</a>). Should you have any more detailed questions, please contact our sales offices.
- 5. We constantly strive to improve our products. Consequently, the products described in this publication may change from time to time. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also reserve the right to discontinue production and delivery of products. Consequently, we cannot guarantee that all products named in this publication will always be available.

The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

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